09/782441 FEB 1 7 2004 Applicant:

**PATENT** 

<u>IN THE UNITED STATES PATENT AND TRADEMARK OFFICE</u>

Wing-Cheong G. Lai et al.

Examiner: Tuan Quach

Serial No.:

09/782441

Filed:

Group Art Unit: 2814

February 13, 2001

Docket: 303.261US2

Title:

SMALL GRAIN SIZE, CONFORMAL ALUMINUM INTERCONNECTS AND

METHOD FOR THEIR FORMATION

## COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

Serial/Patent No. 09/782498

Filing Date February

Attorney Docket 303.261US3

Title

13, 2001

SMALL GRAIN SIZE, CONFORMAL **ALUMINUM INTERCONNECTS AND** METHOD FOR THEIR FORMATION

Respectfully submitted,

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Date 13 Fee

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313day of February, 2004.

Signature

Name